



Legislation Details (With Text)

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In control: Board of Commissioners

On agenda: 12/3/2018

Final action:

Title: Proposed 2019A GO Public Improvement Bonds (associated with the approved 2012 Wake Tech and 2013 School bond referenda) and 2019B GO Refunding Bonds

Sponsors:

Indexes:

Code sections:

Attachments: 1. 20181203 Item Summary - 2019AB GO Bonds.pdf, 2. 20181203 Board Presentation - 2019AB GO Bonds.pdf, 3. 20181203 Attachment 1 - 2019A Issuance Resolution.pdf, 4. 20181203 Attachment 2 - 2019B Bond Order.pdf, 5. 20181203 Attachment 3 - Sworn Statement of Debt.pdf, 6. 20181203 Attachment 4 - Statement of Total Estimated Interest.pdf, 7. 20181203 Attachment 5 - 2019B Issuance Resolution.pdf, 8. 20181203 Attachment 6 - Projects Funded by 2016 and 2017 Notes.pdf, 9. 20181203 Attachment 7 - Escrow Agreement to Retire 2009B Bonds.pdf

Date	Ver.	Action By	Action	Result
12/3/2018	1	Board of Commissioners	accepted	

Proposed 2019A GO Public Improvement Bonds (associated with the approved 2012 Wake Tech and 2013 School bond referenda) and 2019B GO Refunding Bonds

That the Board of Commissioners adopts attached bond order and resolutions which:

- 1. Authorizes the sale and issuance of Series 2019A General Obligation Public Improvement Bonds ("2019A Bonds") in an amount not to exceed \$169,240,000 to refinance the County's Series 2016A&B Bond Anticipation Notes ("2016 Notes") and 2017A&B Bond Anticipation Notes ("2017 Notes") previously issued for school and community college capital needs and to provide additional funds for such purpose;**
- 2. Authorizes Series 2019B General Obligation Refunding Bonds ("2019B Bonds") in an amount not to exceed \$125,000,000 to refinance certain maturities of the County's Series 2009B General Obligation Bonds ("2009B Bonds");**
- 3. Directs filing of Sworn Statement of Debt and Statement of Estimated Interest with the Board Clerk; and**
- 4. Authorizes the sale and issuance of the Series 2019B General Obligation Refunding Bonds described in item 2 above**